

Cryogenic Operation of Field Programmable Gate Arrays

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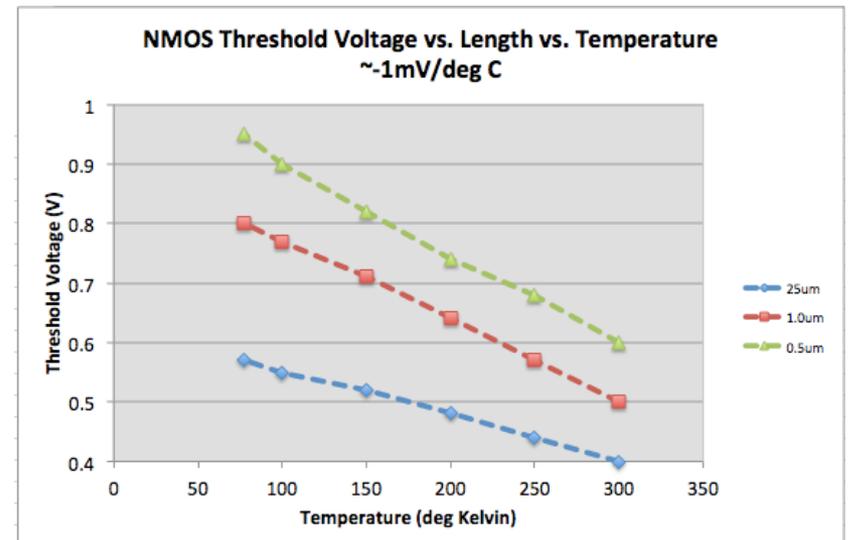
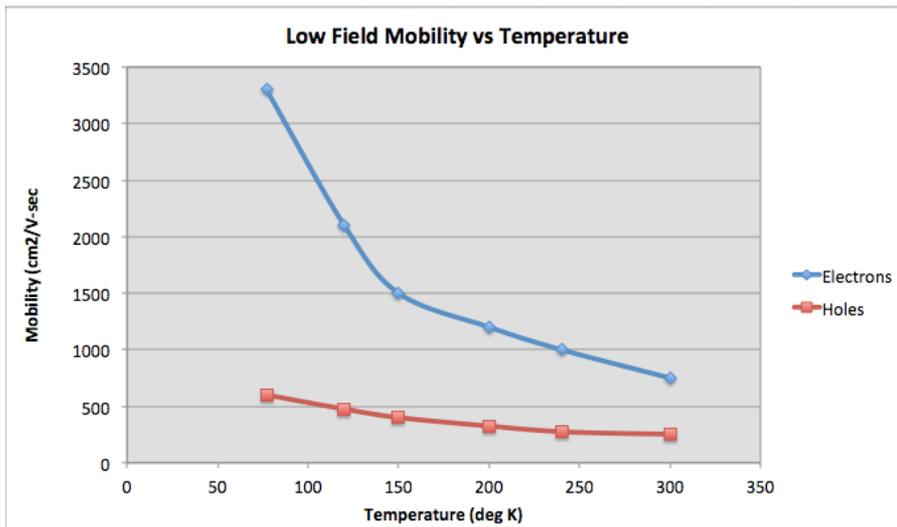
Cryogenic & Extreme Environments

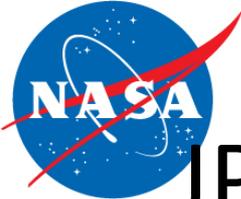
- Many deep space applications require exposure to extreme cold.
 - Mars: -130C to 20C
 - Titan: -180C
 - Europa:-160C
 - Moon: -230C to 130C
- Electronics need to be able to function for long periods of time in cryogenic conditions
- New mission architectures are enabled:
 - Science instrumentation can be moved into sample environment
 - Distributed motor control allows for improved performance and control.
 - Overall system weight and power requirements can be positively impacted.



Low Temperature CMOS Overview

- Electron mobility increases significantly
 - Phonon contribution (lattice scattering) to mobility decreases as temperature decreases, mobility increases
- Threshold voltage increases $\sim 1\text{mV}/^\circ\text{C}$ for both NMOS and PMOS
- Subthreshold slope and CMOS inverter propagation decrease $\sim 10\text{-}20\%$ at 100°K



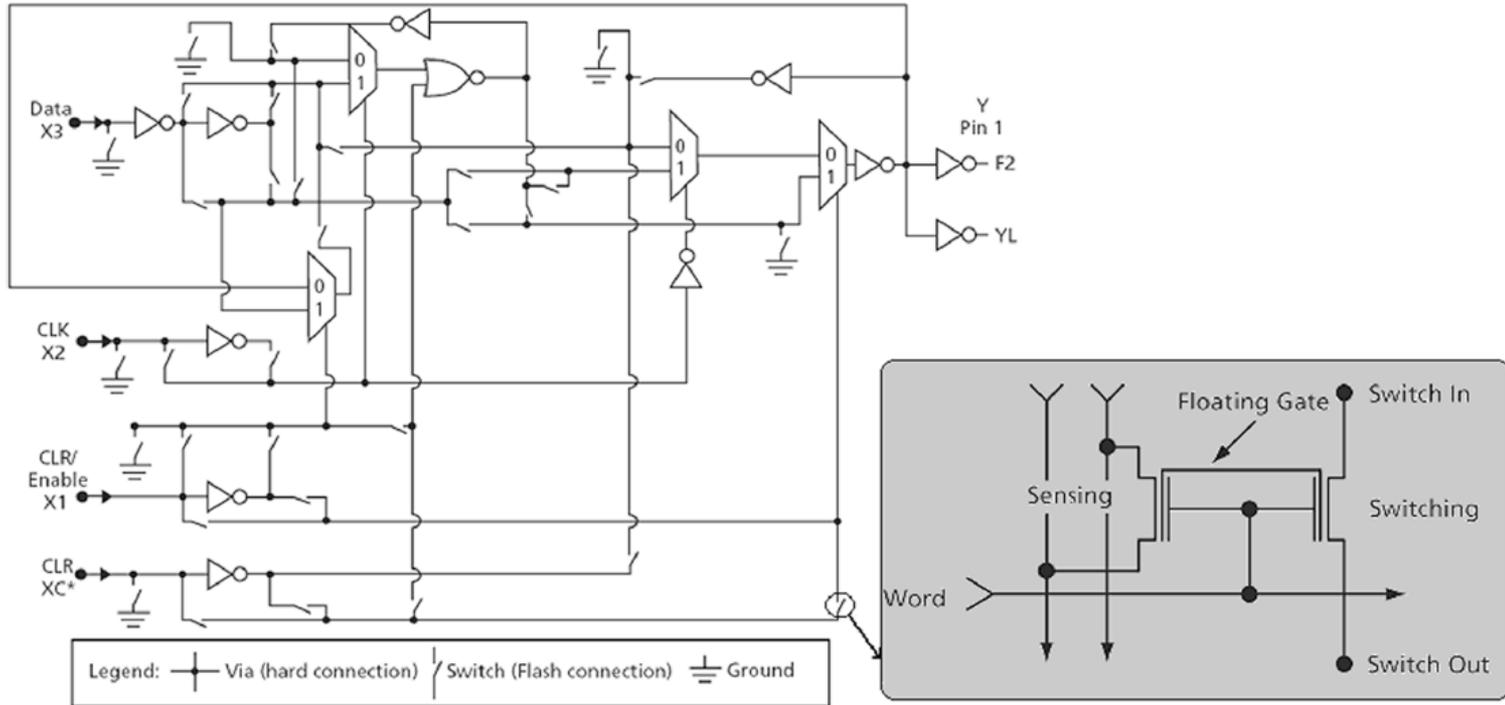


JPL FPGA Cryogenic Characterization

	Vendor	FPGA	Technology	Core Voltage
Previous work	Microsemi	AS54SX32A	250nm	3.3V
	Xilinx	XCVR300	220nm	2.5V
	Xilinx	XC2VP20	180nm	1.8V
This work	Microsemi	AX500	180nm	1.5V
	Microsemi	AGLN250V2	130nm	1.2V
	Microsemi	AGL125	130nm	1.2V
	Microsemi	AGL1000	130nm	1.2V
	Xilinx	XC3S250	90nm	1.2V
	Xilinx	XCV5VLX30	65nm	1.0V



Microsemi Flash based FPGA



Microsemi IGLOO Flash FPGAs			
	AGL125	AGLN250	AGL1000
System Gates	125,000	250,000	1,000,000
D- Flip Flops	3,072	6,144	24,576
RAM Kb	18	36	144



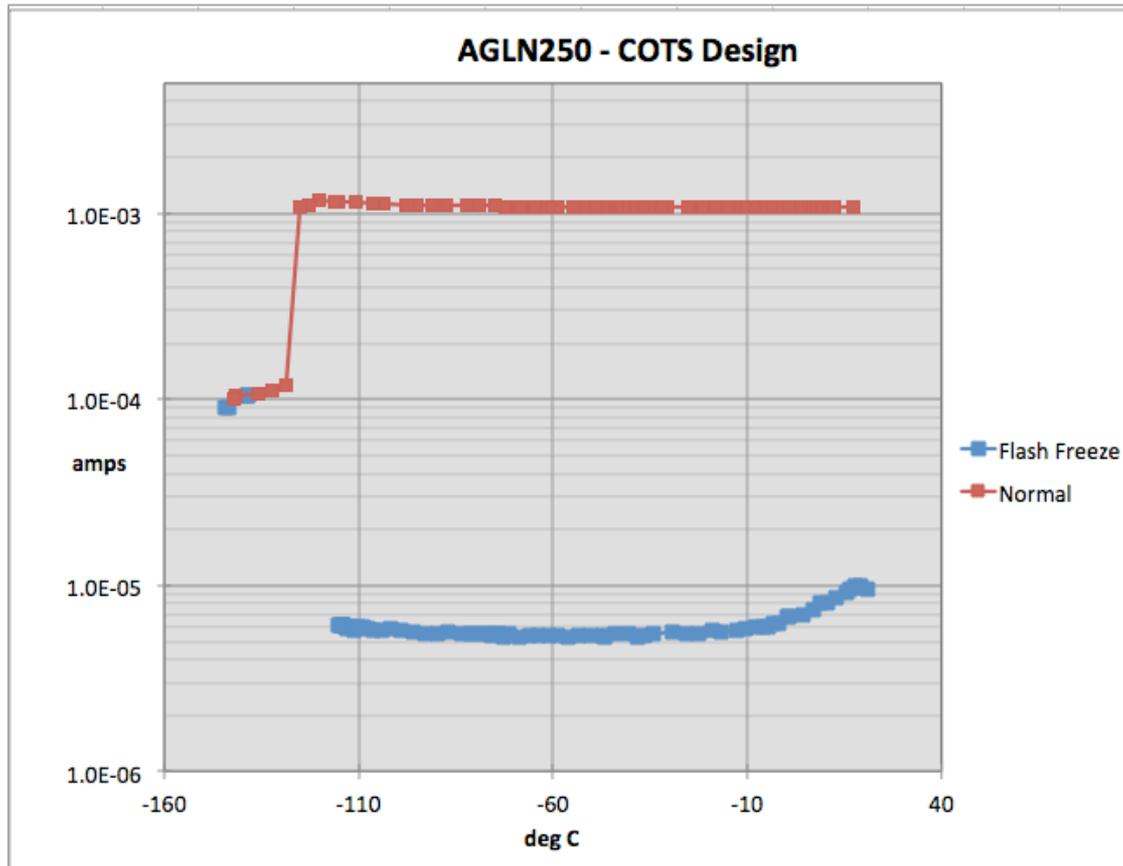
AGL125 and AGL250N Characterization

- Initial devices chosen to test for functionality
- Test variation of COTS versus custom board materials and devices.
- Foundation for low temperature FPGA design rules.

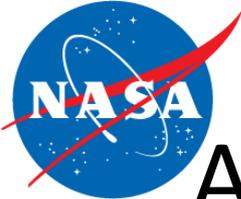
Design	Details	Goal
Gate Delay	Long chain ring oscillators	Setup/hold time as function of temperature
Large Scale Integrity	Two large counters and comparator run at max rate	Stability of performance over temperature
Low Power Dynamic	A small amount of logic at small clock rate is used to generate a heartbeat pulse.	Measure static power as a function of temperature while checking the fpga is still 'alive'
High Power Dynamic	A large circuit running at max clock rate is used to generate maximum dynamic power.	Characterize overall power consumption



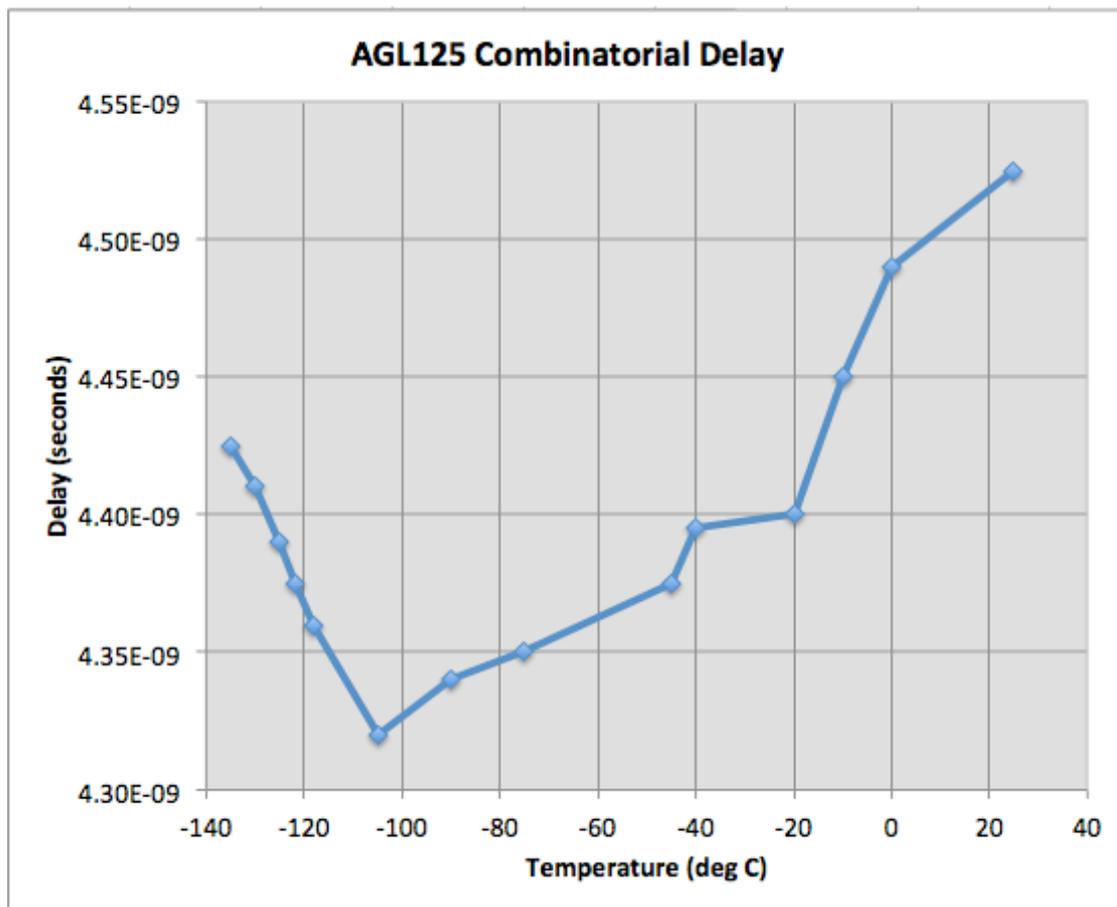
AGLN250 – COTS Design



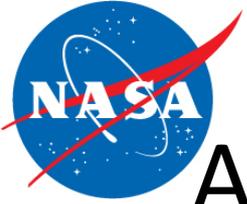
- Test COTS parts and PCB capability.
- Flash Freeze mode retains all SRAM and register and I/O original states.
- I/Os and clocks connected to the FPGA can still be toggled without impact on device power consumption.
- Drop in current unexplained.
- All devices on PCB were operating nominally.



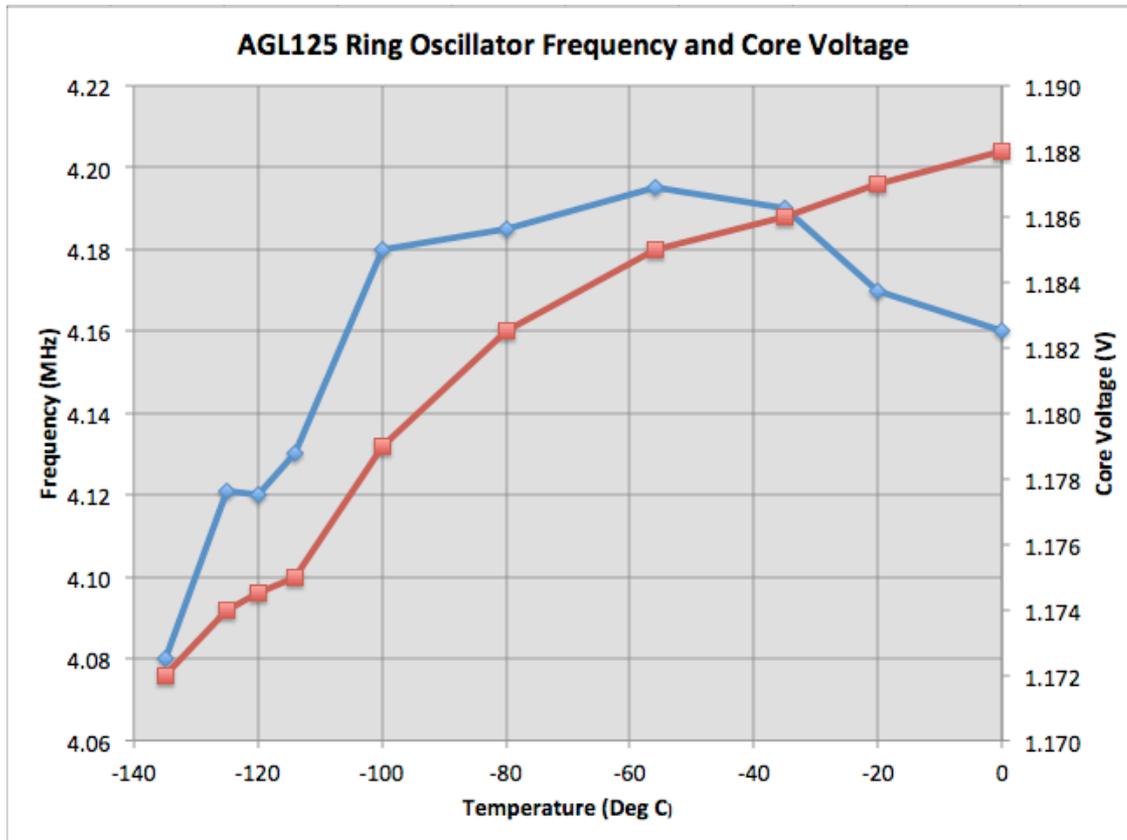
AGL125 – Custom Design/COTS PCB



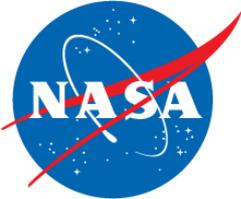
- Combinatorial logic delay measured.
- Accuracy of reference clock and possible droop in 1.2V supply are concerns.
- At -150C FPGA started generating 'strange' symbols and stopped transmitting and USB connection was lost.
- Temperature raised to -100C and returned to operation.
- USB chip ceased operation.
- Clock chip went into quasi-permanent low speed mode.



AGL125 – Custom Design/COTS PCB



- Ring oscillator frequency peaks near -60C and slows down.
- Decrease in core voltage as a function of temperature will influence ring oscillator results.
- On board 20MHz clock became unstable at -80C



FPGA Based Microtransceiver

Low-volume, low-power, ultra-high frequency radio transceiver

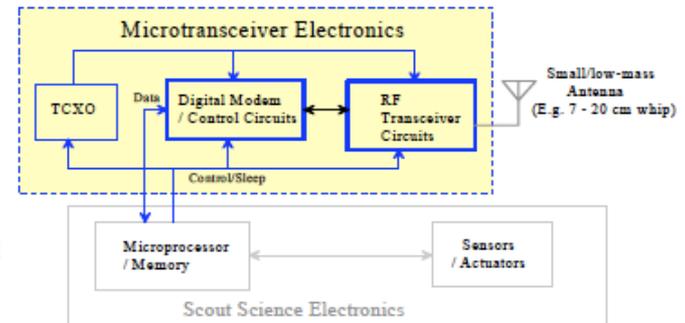
Parameter	Value
Tx/Rx Frequency	390-410/430-450 MHz
Tx/Rx Modulation	BPSK-QPSK/BPSK
Tx/Rx bit rate	256/8 kbps
Rx sensitivity	-120dBm
Tx power	10mW to 1W

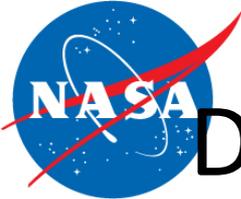


REQUIRED CAPABILITIES

- NEAR-CONTINUOUS RECEIVE CAPABILITY
- SYMMETRIC AND ASYMMETRIC MODULATIONS
- LOW POWER REQUIREMENTS
- VARIABLE DATA RATES

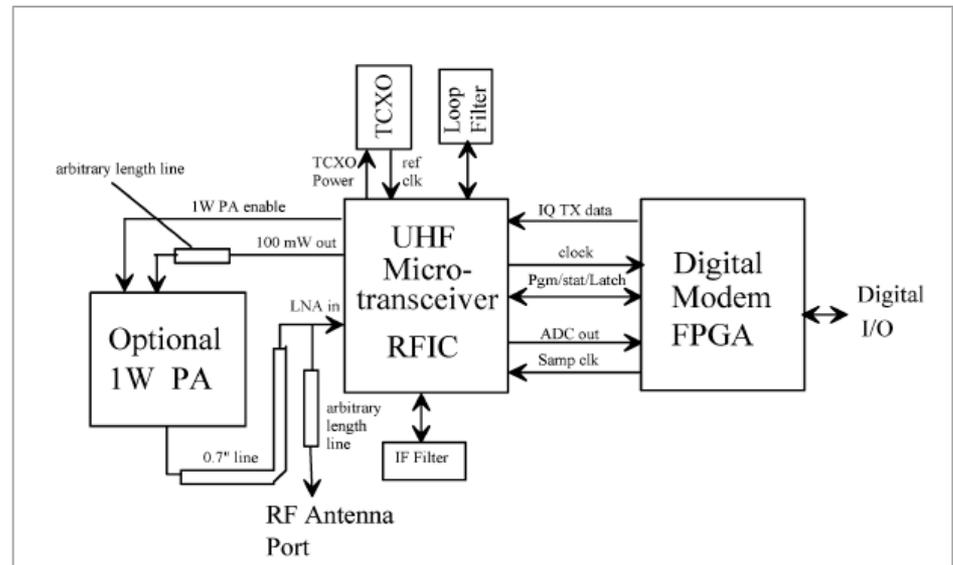
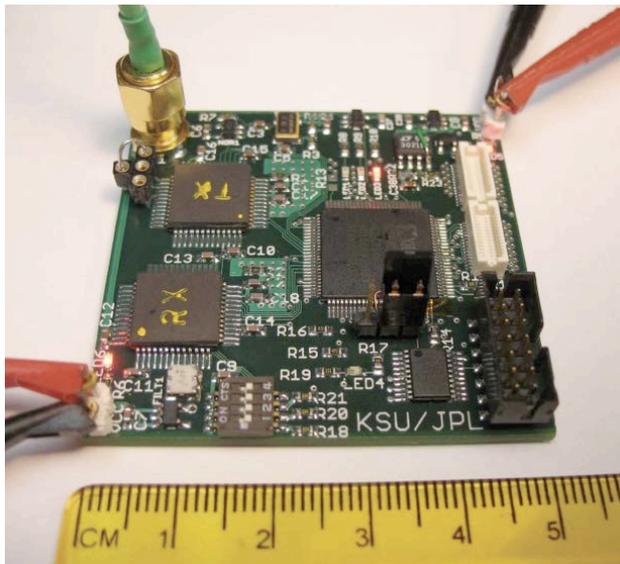
- TARGETED IN SITU LINKS FOR DISTRIBUTED SENSORS AND SENSOR NETWORKS
- PRIMARY: LANDED SENSOR-TO-ORBITER
- SECONDARY: SENSOR-TO-SENSOR





Digital Modem for Microtransceiver

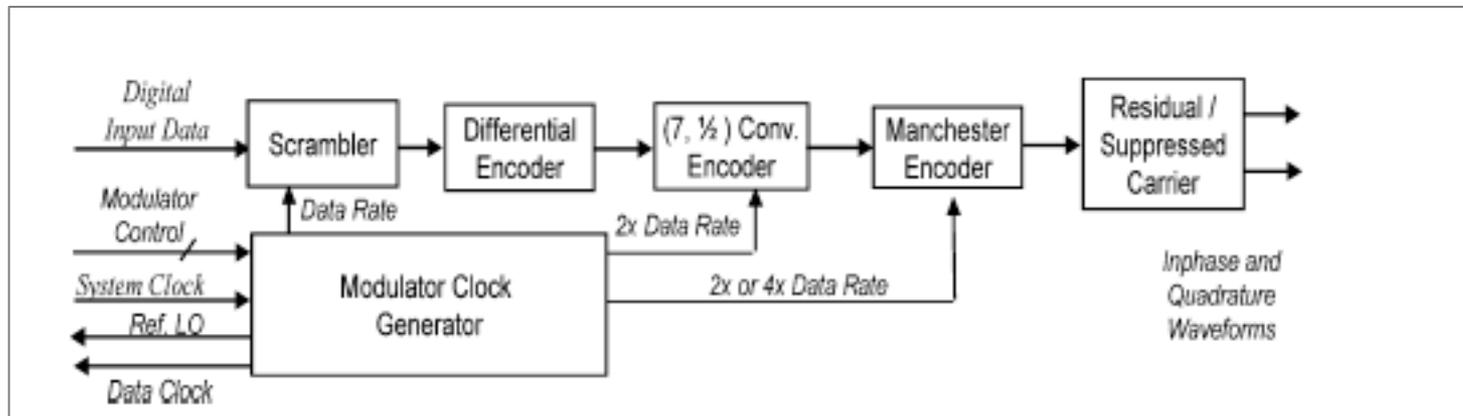
- All aspects of digital modem functions implemented in FPGA
 - Scrambler
 - Encoding
 - Clock generation
 - I/O timing control
- Initially implemented in Xilinx Spartan 3E
- Re-done in Microsemi AGL1000

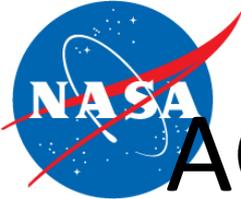




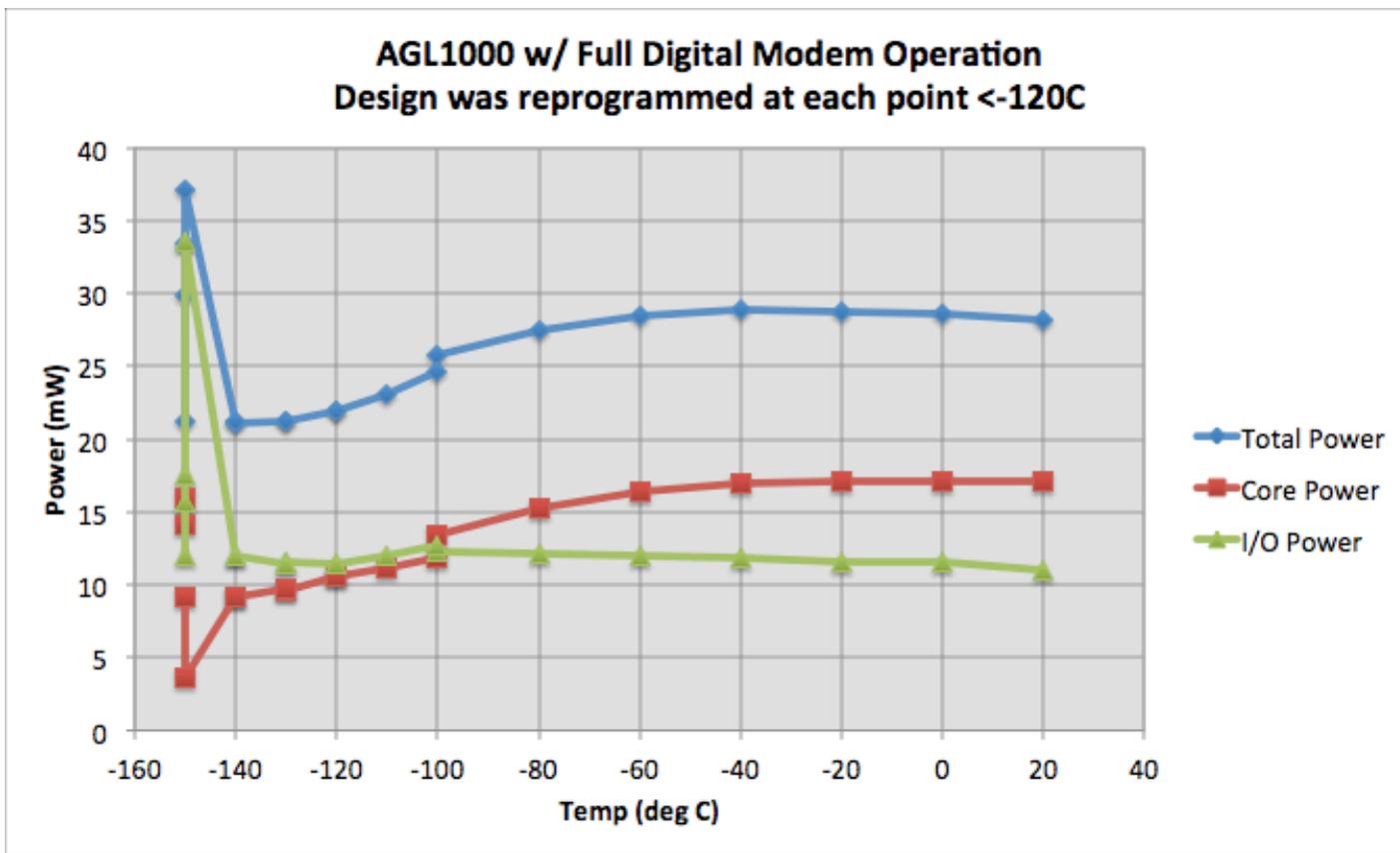
FPGA Digital Modem

- The digital modem formats data bits for transmit and provides signal demodulation and bit/frame synchronization functions during receive.
- Responsible for programming the various registers of the RFIC and for interfacing with the host microcontroller aboard a scoutcraft or an external sensor.
- In transmit mode, provides forward error correction (FEC) convolutional coding compatible with Proximity-1 protocols, and optional packet framing functions.
- In receive mode, provides the demodulation task as well as bit/frame synchronization

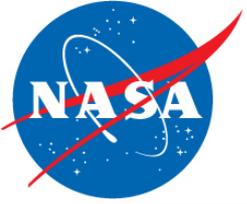




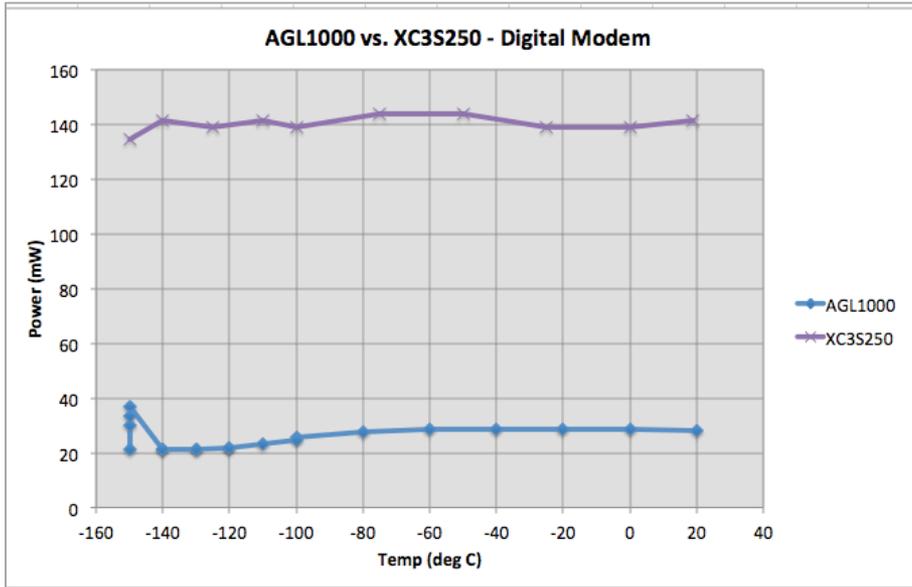
AGL1000 – Digital Modem Design



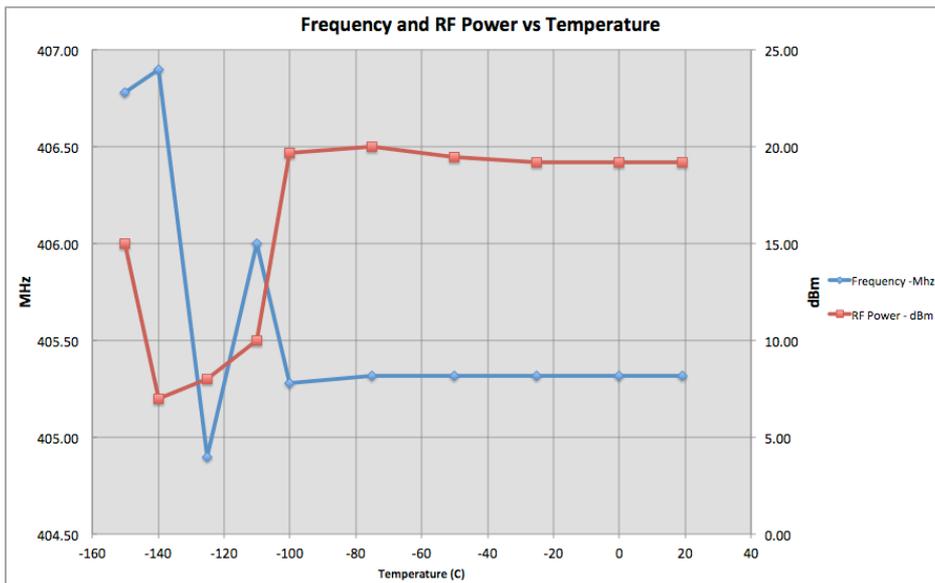
- IO power shows unexplained 3X spike at -145C
- Core power begins to decrease after -40C
- Reprogramming device 'reset' power curve



AGL1000 vs. XC3S250



- AGL1000 has 9X reduction in overall power compared to the XC3S250.
- XC3S250 power remains constant $\pm 2\%$.
- RF power constant until -100C and then it reduces 60%.





AX500 Design

- AX500:
 - 500K gates/5.3K FF/73Kb Core RAM
 - No SEU enhanced CLK or TMR FF
 - PQ208 package
- Pulse Width Modulator circuit:
 - 5/10 KHz PWM resolver frequency controlled via test instruments.
 - Using internal AX500 PLLs, 50 & 100 MHz clock outputs are generated from the 100 MHz on the board oscillator



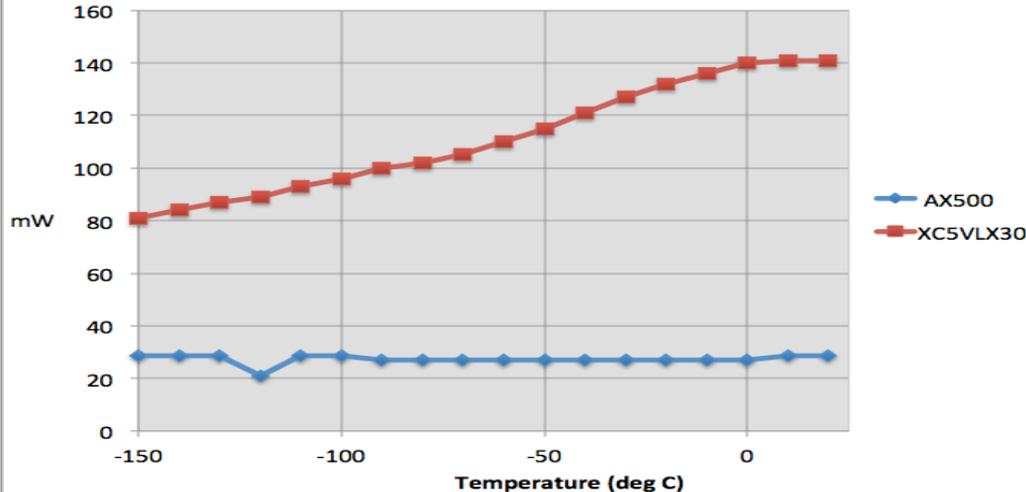
XC5VLX30 Design

- XC5VLX30:
 - 4.8K slices/30K Logic cells/19.2K FF/1.1Mb BRAM
 - 4 DCM/2 PLL
 - FF324 Package
- Stability and performance of:
 - Internal PLLs
 - Ring oscillator
 - Combinatorial logic circuits
 - Same PLL was used to both divide and multiply the master on-board oscillator to generate the 50/150 MHz clocks.

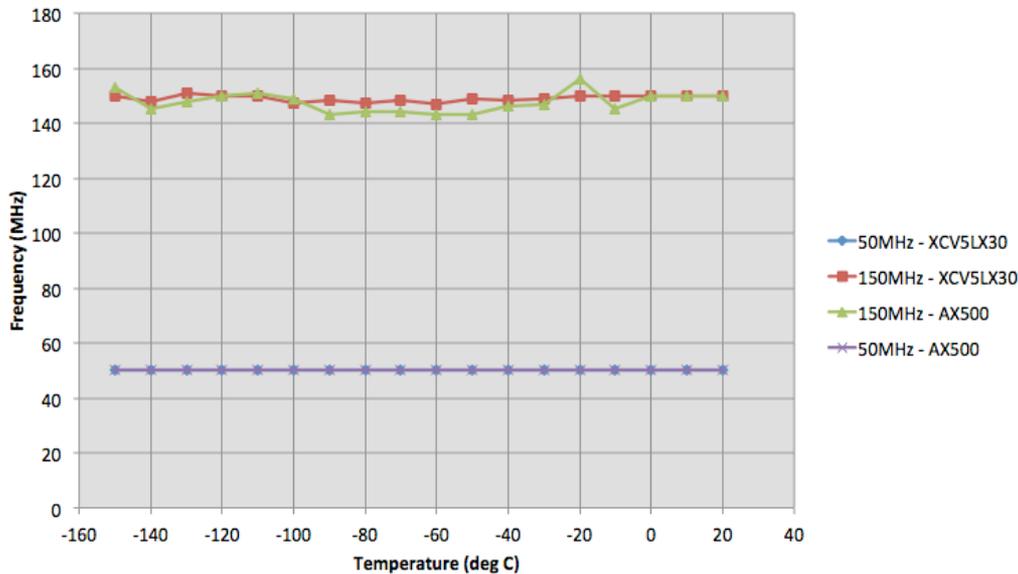


AX500 and XCV5LX30 Test Results

FPGA Core Power vs. Temperature



Clock Frequency vs FPGA vs Temperature



- 150MHz AX500 clock variation is $\pm 4.5\%$, 150MHz XCV5LX30 is $\pm 2\%$
- 50MHz clocks on both devices is $< 0.1\%$ variation.
- XCV5LX30 core power drops 66% at -150°C .
 - Slice LUT resource utilization is $< 1\%$. Current is dominated by leakage current which is temperature sensitive.
- AX500 power is independent of temperature.
 - R & C cell utilization is 10%. Leakage current is masked by functional current.
- External program FLASH memory became unstable at -110°C and failed at -130°C .



FPGA Characterization Summary down to -150C

	Vendor	FPGA	PCB	Results
Previous work	Microsemi	AS54SX32A	Custom	Functional
	Xilinx	XCVR300	Custom	Functional and reprogrammable. Large surge, temperature dependent surge current.
	Xilinx	XC2VP20	Custom	Functional and reprogrammable
This work	Microsemi	AX500	Custom	Functional <5% variation of 150MHz clock, power independent of temperature
	Microsemi	AGLN250V2	COTS	Functional with 10X current drop at -130C. Flash freeze functional with 100X in reduction in standby current.
	Microsemi	AGL125	COTS	Functional and reprogrammable to -140C, clock stability issues at -120C
	Microsemi	AGL1000	Custom	Functional digital modem to -130C, core power drops 30% at -140C,
	Xilinx	XC3S250	Custom	Functional <2% change in power down to -150C
	Xilinx	XCV5VLX30	Custom	Functional and reprogrammable. Core current drops 66% at -150C. On board flash failed @ -130C



Summary and Conclusions

- A variety of FPGA technologies (antifuse, flash, SRAM) were tested down to -150C.
- FPGAs from all technologies operated down to -150C.
 - One flash based design stopped working at -130C, other designs continued to work at -150C
- Flash and SRAM based FPGAs can be reprogrammed successfully down to -150C.
- Core power can vary significantly over temperature.
- Accurate predictor of resource utilization and die size is currently not available.
- Successful cryogenic FPGA operation will require custom support part screening.
 - The FPGA may work but surrounding devices can fail leading to FPGA failure.
- Accurate cryogenic simulation models are needed for final flight designs.
 - Standard manufacturing models need to be extended to include such data as internal timing changes of the logic and path delays versus the temperature.